Spherical Boron Nitride

Specification

GBN-60

Product Features

High thermal conductivity, low dielectric constant, lower specific surface area compared with plate boron nitride。

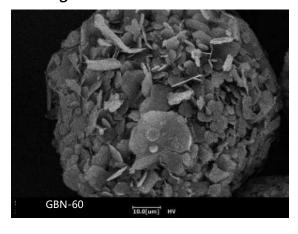
Application

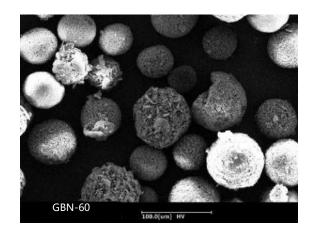
For thermal interface material with lower dielectric constant or higher dielectric resistance, such as thermal pad, thermal conductive prepreg,thermal conductive plastic.

Typical Properties

Item		Unit	Typical Value	Method/Device
Particle Size	(D ₅₀)	μm	68.38	Light Scattering/Bettersize2600
S.S.A.		m²/g	1.78	BSD-BET-400/ Specific Surface Area Analyzer
Electrical Conductivity		μS/cm	20.2	Mettler FE-38/ Conductivity Meter
рН		-	9.03	Mettler FE-28 / pH Meter
Tap Density		g/cm ³	0.43	BT-313/ tap density tester

SEM Image





Typical Packaging

10Kg/Bag

Paper outer bag + PE inner bag + cardboard boxes

Period of Validity

It is recommended to use this product within 12 months. If it is overdue, the product quality status shall be re evaluated.

Handling and Storage

When using, wear a dust mask to prevent dust inhalation.

Keep the container sealed and stored in a cool, dry and well ventilated area.

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